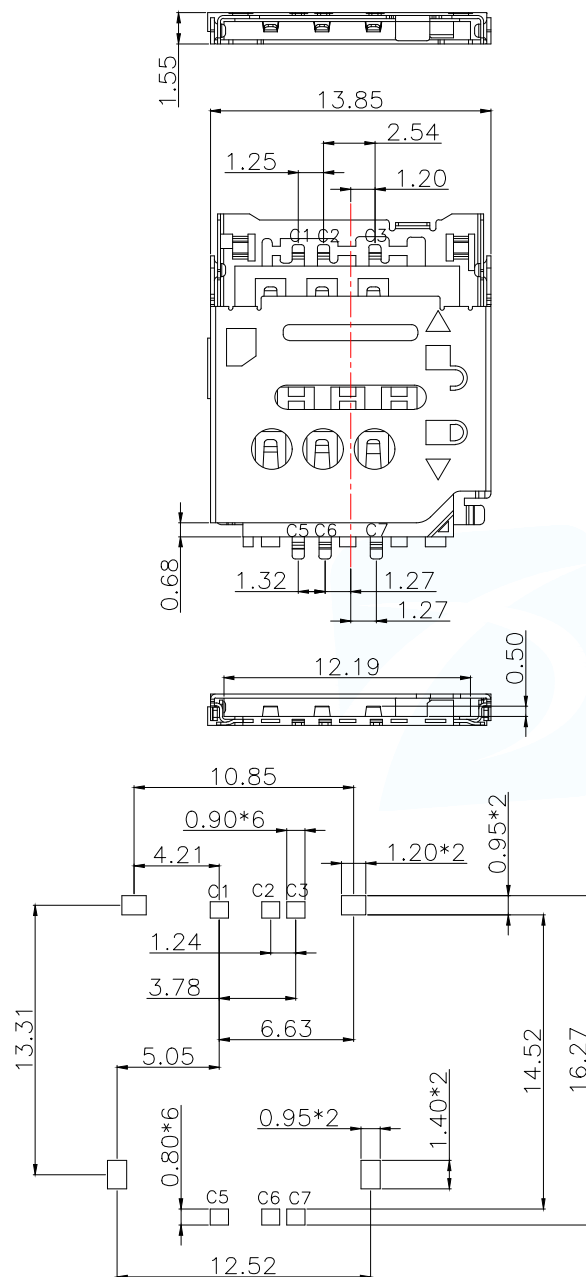
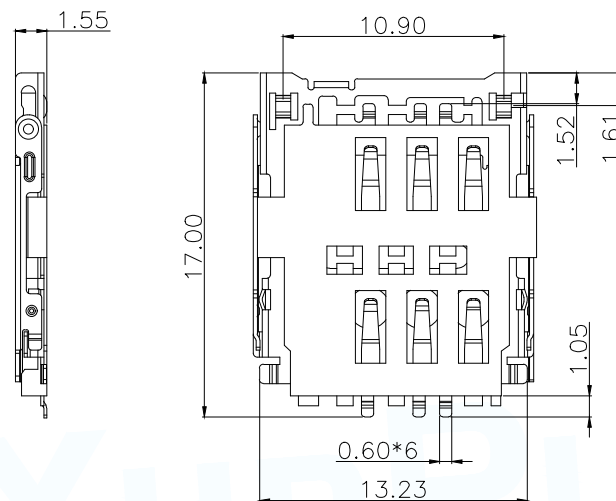


x0W01.00



PCB 焊盘

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05 

Specification

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0.

Contact: Copper Alloy

SHELL: SUS

PLATING:

Contact: Plated 50u" Ni Overall Contact Au 1u, Pad Au 0.8u

Shell: clean

Electrical:

Current Rating :0.5Amps max

Voltage Rating :5V AC/DC

Ambient Temperature Range : $-40^{\circ}\text{C}\sim+85^{\circ}\text{C}$ Storage Temperature Range : $-40^{\circ}\text{C}\sim+85^{\circ}\text{C}$

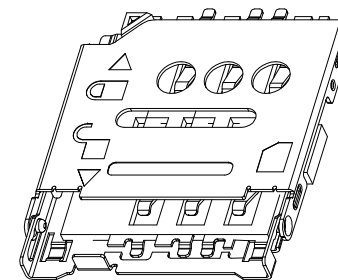
Ambient Humidity Range :95% R.H. Max.

Contact Resistance:80m Ω max.Insulation Resistance:100M Ω min./100V DC

Mating Cycles:5,000 Insertions

Reflow peak temp.: $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$, 3~5 S

PIN NO.	PIN NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: MICRO-SIM 数量1.50H 6P	
DECIMALS:		PAR	SMC-221-CRDP6
ANGLES:		DWN	Lucas
.X: ± 0.15		CHKD	Ethan
.XX: ± 0.10		APVD	Jacob
.XXX: ± 0.05		SCALE 1:1	UNIT:MM
CUSTOMER COPY		SIZE:A4	SHEET:1F1
			REV:A